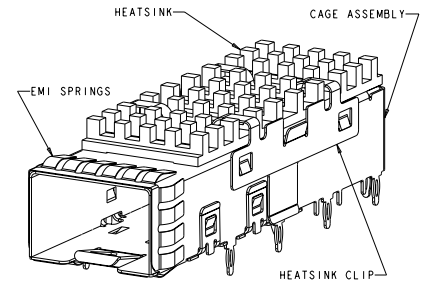
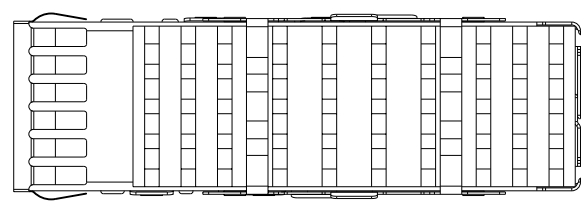
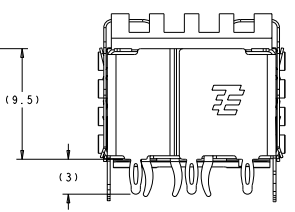
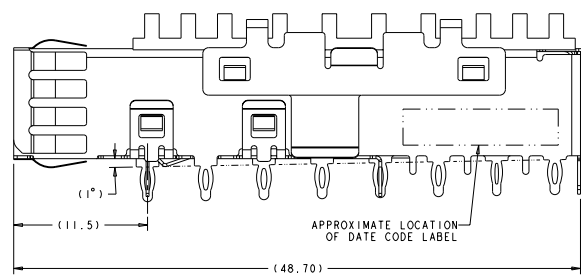
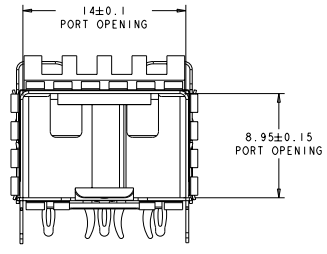


REV	DATE	DESCRIPTION	BY	CHK	APP
C		REVISED PER ECO-09-022874	20070809	CR	MS
D		REVISED PER ECO-10-004036	20080110	CJV	MRS

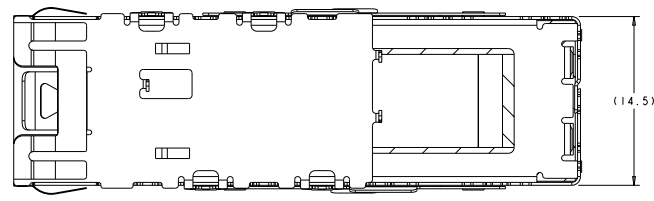
- △ MATERIAL:
CAGE ASSEMBLY - NICKEL-SILVER ALLOY.
EMI SPRINGS - COPPER ALLOY.
HEATSINK - ALUMINUM.
HEATSINK CLIP - STAINLESS STEEL.
- △ FINISH:
HEATSINK - ELECTROLESS NICKEL.
HEATSINK CLIP - PASSIVATE.
EMI SPRINGS - 0.8um MIN TIN OVER 0.8um MIN NICKEL
NON PLATED EDGES PERMISSIBLE.
- 3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- △ PADS AND VIAS CHASSIS GROUND.
- △ DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 6. MINIMUM PCB BOARD THICKNESS:
SINGLE SIDED = 1.50mm
- △ REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.



2007277-1
SCALE 5:1



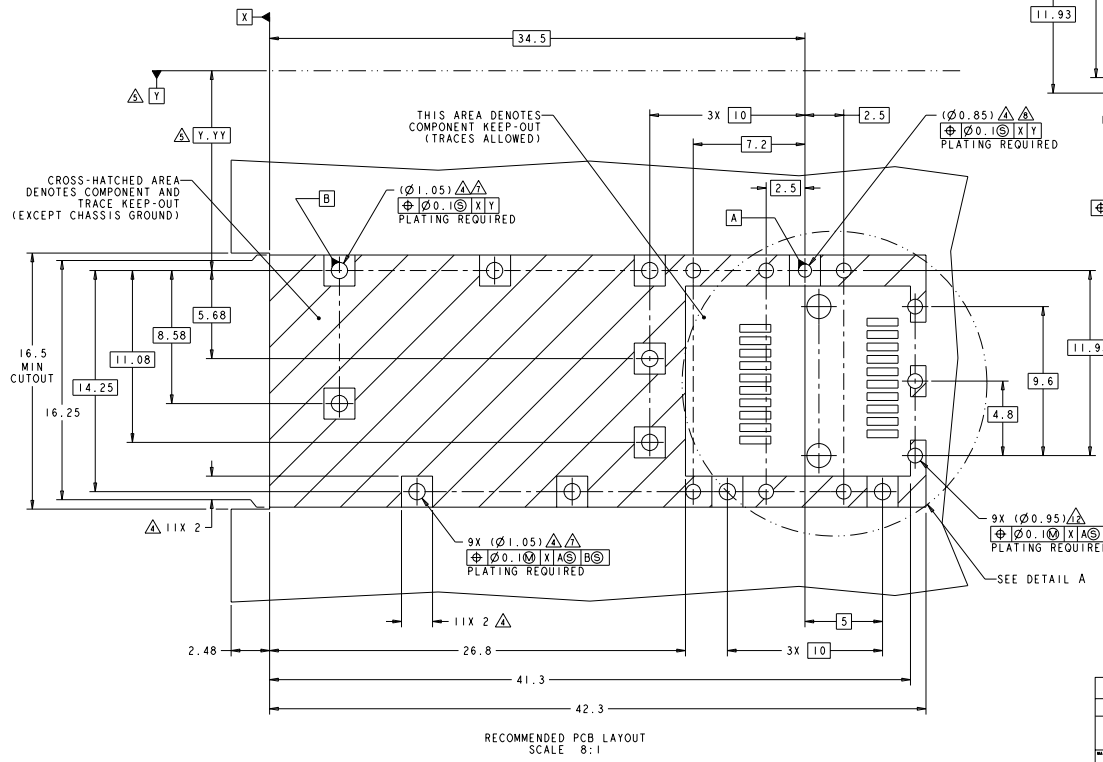
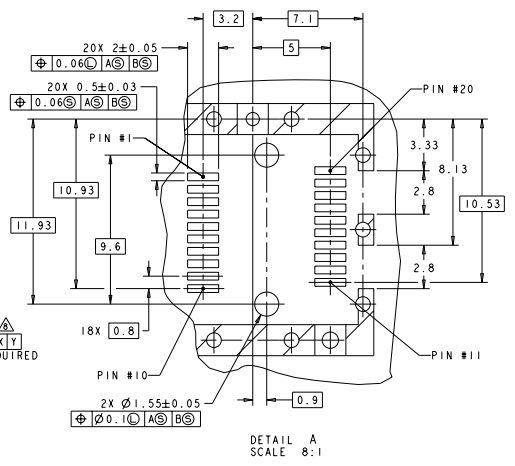
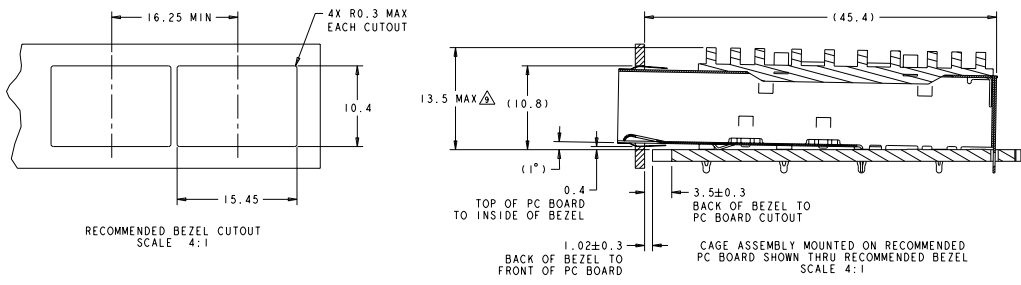
- △ REFERENCE APPLICATION SPEC. 114-13120, HOLE C, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.
- △ DIMENSIONS APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 10. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED
ASSEMBLED.
- 11. NOTE DELETED
- △ REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.



207277-1
PART
NUMBER

DATE: 08/09/07 BY: SCHELLT, K402087 CHECKED: SCHELLT, K402087 TITLE: SFP-1X1 CAGE ASSEMBLY W/ HEATSINK, PCI, PRESS-FIT EXTERNAL EMI SPRING REF: 108-2264 SPECIFICATION SPEC: 114-13120 REV: - CUSTOMER DRAWING		DATE: 08/09/07 BY: SCHELLT, K402087 CHECKED: SCHELLT, K402087 TITLE: SFP-1X1 CAGE ASSEMBLY W/ HEATSINK, PCI, PRESS-FIT EXTERNAL EMI SPRING REF: 108-2264 SPECIFICATION SPEC: 114-13120 REV: - CUSTOMER DRAWING		DATE: 08/09/07 BY: SCHELLT, K402087 CHECKED: SCHELLT, K402087 TITLE: SFP-1X1 CAGE ASSEMBLY W/ HEATSINK, PCI, PRESS-FIT EXTERNAL EMI SPRING REF: 108-2264 SPECIFICATION SPEC: 114-13120 REV: - CUSTOMER DRAWING	
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REV	DATE	DESCRIPTION	BY	CHK	APP
00		SEE SHEET 1			



REV	DATE	DESCRIPTION	BY	CHK	APP
00		SEE SHEET 1			

DATE	08/24/2018	BY	PCB ELECTRONICS CORPORATION
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